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(72) Inventors: **SHEN, Sheng**; c/o Carnegie Mellon University, 5000 Forbes Avenue, Pittsburgh, Pennsylvania 15213 (US). **CHENG, Rui**; c/o Carnegie Mellon University, 5000 Forbes Avenue, Pittsburgh, Pennsylvania 15213 (US).

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(74) Agent: **CARLETON, Dennis M.** et al.; Kdw Firm PLLC., 2601 Weston Parkway, SUITE 103, Cary, North Carolina 27513 (US).

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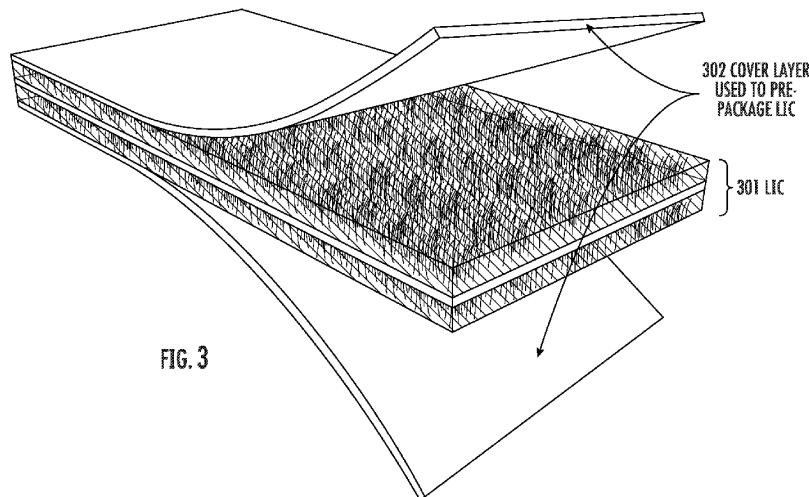
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(71) Applicant: **CARNEGIE MELLON UNIVERSITY**

[US/US]; 5000 Forbes Avenue, Pittsburgh, Pennsylvania 15213 (US).

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(54) Title: LIQUID-INFUSED MICRO- OR NANO-STRUCTURED METAL COMPOSITE



(57) Abstract: A liquid-infused composite comprising a thermally conductive and micro- or nano-structured scaffold infused with an effective amount of thermal bridge liquid, with the scaffold primarily comprising a first metal, having a micro- or nano-structure, being capable of holding the thermal bridge liquid internally, and having a self-supporting interconnected network structure. The composite allows easy pre-packaging, offers high thermal performance, reworkability, and reliability, and may be used for thermal interface cooling in data centers, GPU/CPU systems, solid-state lasers, thermoelectric modules, LEDs, etc.

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